

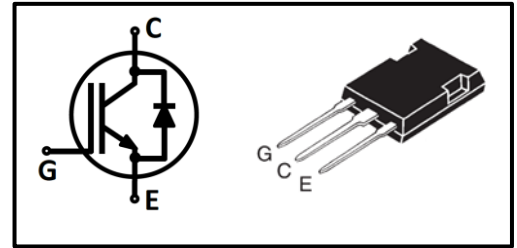
Features

- Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Low V_{CEsat} , fast switching
- High ruggedness, good thermal stability
- Very tight parameter distribution

Type	Marking	Package Code
MPBQ100N120E	MP100N120E	TO-247-3L Plus

Applications

- Industrial UPS
- Charger
- Energy Storage
- Welding



Maximum Rated Values

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current, limited by T_{vjmax} $T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	I_C	200 100	A
Pulsed collector current, t_p limited by $T_{vjmax}^{1)}$	I_{Cpuls}	400	
Diode forward current, limited by T_{vjmax} $T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	I_F	200 100	
Diode pulsed current, t_p limited by $T_{vjmax}^{1)}$	I_{Fpuls}	400	V
Gate-emitter voltage	V_{GE}	± 20	
Transient Gate-emitter voltage ($t_p \leq 10\mu\text{s}, D < 0.01$)		± 30	
Power dissipation $T_C=25^\circ\text{C}$	P_{tot}	1070	W
Power dissipation $T_C=100^\circ\text{C}$		535	
Operating junction temperature	T_{vj}	-40~175	°C
Storage temperature	T_{stg}	-55~150	
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	

¹⁾ Defined by design. Not subject to production test.



Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
IGBT thermal resistance, junction-case	R_{thJC}	-	-	0.14	K/W
Diode thermal resistance, junction-case	R_{thJCD}	-	-	0.22	
Thermal Resistance, junction-ambient	R_{thJA}	-	-	40	

Electrical Characteristics (at $T_{vj}=25^{\circ}C$, unless otherwise specified) Static Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.25mA$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=100A$ $T_{vj}=25^{\circ}C$	-	1.70	1.95	
		$T_{vj}=125^{\circ}C$	-	2.01	-	
		$T_{vj}=150^{\circ}C$	-	2.09	-	
		$T_{vj}=175^{\circ}C$	-	2.15	-	
G-E threshold voltage	$V_{GE(th)}$	$I_C=2.4mA, V_{CE}=V_{GE}$	4.8	5.4	6.0	mA
C-E leakage current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_{vj}=25^{\circ}C$	-	-	0.1	
		$T_{vj}=175^{\circ}C$	-	-	4.0	
G-E leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	250	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=40A$	-	35	-	S

Dynamic Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input capacitance	C_{ies}	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	15370	-	pF
Output capacitance	C_{oes}		-	377	-	
Reverse transfer capacitance	C_{res}		-	116	-	
Gate charge	Q_G	$V_{CC}=600V,$ $I_C=100A,$ $V_{GE}=15V$	-	583	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13	-	nH



IGBT Switching Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Turn-on delay time	$t_{d(on)}$	$T_{vj}=25^{\circ}C,$ $V_{CC}=600V,$ $I_C=100A,$ $V_{GE}=0V/15V,$ $R_G=10\Omega,$ Inductive load	-	172	-	ns	
Rise time	t_r		-	112	-		
Turn-off delay time	$t_{d(off)}$		-	600	-		
Fall time	t_f		-	116	-		
Turn-on energy	E_{on}		$T_{vj}=175^{\circ}C,$ $V_{CC}=600V,$ $I_C=100A,$ $V_{GE}=0V/15V,$ $R_G=10\Omega,$ Inductive load	-	8.9	-	mJ
Turn-off energy	E_{off}			-	6.2	-	
Total switching energy	E_{ts}			-	15.2	-	
Turn-on delay time	$t_{d(on)}$	$T_{vj}=175^{\circ}C,$ $V_{CC}=600V,$ $I_C=100A,$ $V_{GE}=0V/15V,$ $R_G=10\Omega,$ Inductive load	-	151	-	ns	
Rise time	t_r		-	116	-		
Turn-off delay time	$t_{d(off)}$		-	707	-		
Fall time	t_f		-	142	-		
Turn-on energy	E_{on}		$T_{vj}=175^{\circ}C,$ $V_{CC}=600V,$ $I_C=100A,$ $V_{GE}=0V/15V,$ $R_G=10\Omega,$ Inductive load	-	14.0	-	mJ
Turn-off energy	E_{off}			-	8.3	-	
Total switching energy	E_{ts}			-	22.3	-	

Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode forward voltage	V_F	$V_{GE}=0V, I_F=100A$ $T_{vj}=25^{\circ}C$	-	2.1	-	V
		$T_{vj}=150^{\circ}C$	-	2.0	-	
		$T_{vj}=175^{\circ}C$	-	1.9	-	
Diode reverse recovery time	t_{rr}	$T_{vj}=25^{\circ}C,$ $V_R=600V,$ $I_F=100A,$ $di_F/dt=600A/\mu s$	-	361	-	ns
Diode reverse recovery charge	Q_{rr}		-	5.7	-	μC
Diode peak reverse recovery current	I_{rrm}		-	31	-	A
Diode reverse recovery time	t_{rr}	$T_{vj}=175^{\circ}C,$ $V_R=600V,$ $I_F=100A,$ $di_F/dt=600A/\mu s$	-	677	-	ns
Diode reverse recovery charge	Q_{rr}		-	15.9	-	μC
Diode peak reverse recovery current	I_{rrm}		-	58	-	A

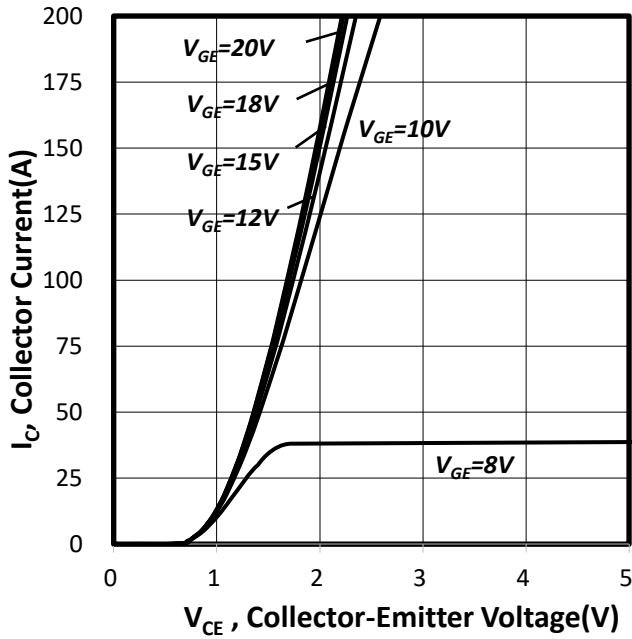


Figure 1. Typical output characteristic ($T_{vj}=25^{\circ}\text{C}$)

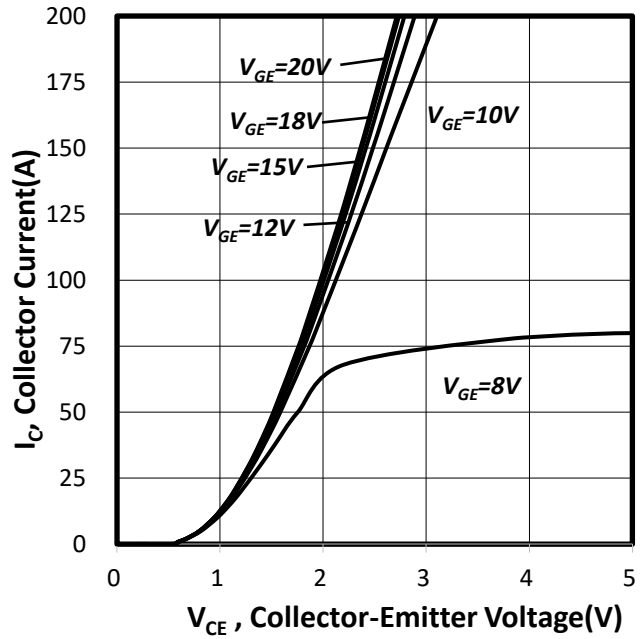


Figure 2. Typical output characteristic ($T_{vj}=125^{\circ}\text{C}$)

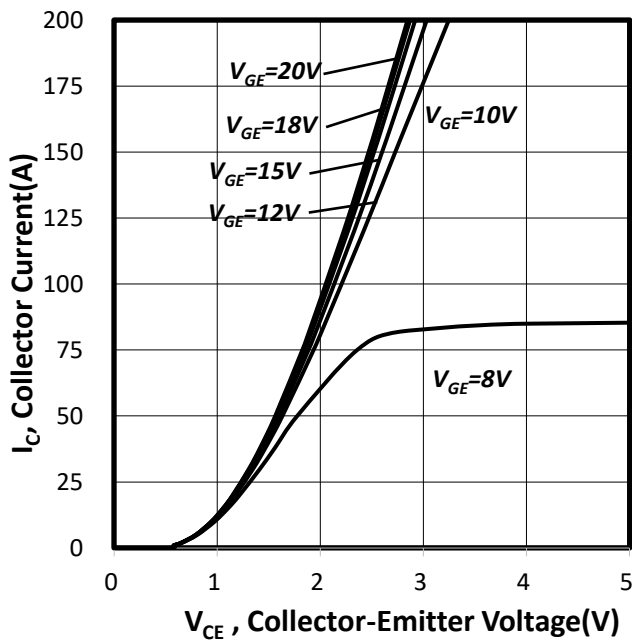


Figure 3. Typical output characteristic ($T_{vj}=150^{\circ}\text{C}$)

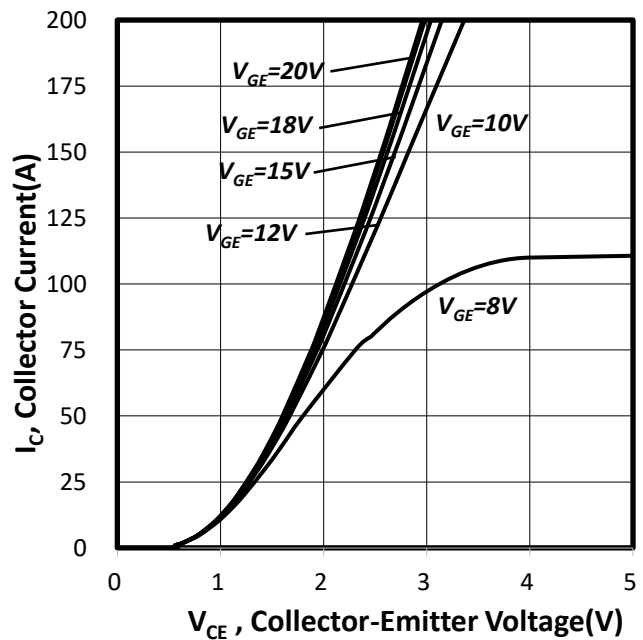


Figure 4. Typical output characteristic ($T_{vj}=175^{\circ}\text{C}$)

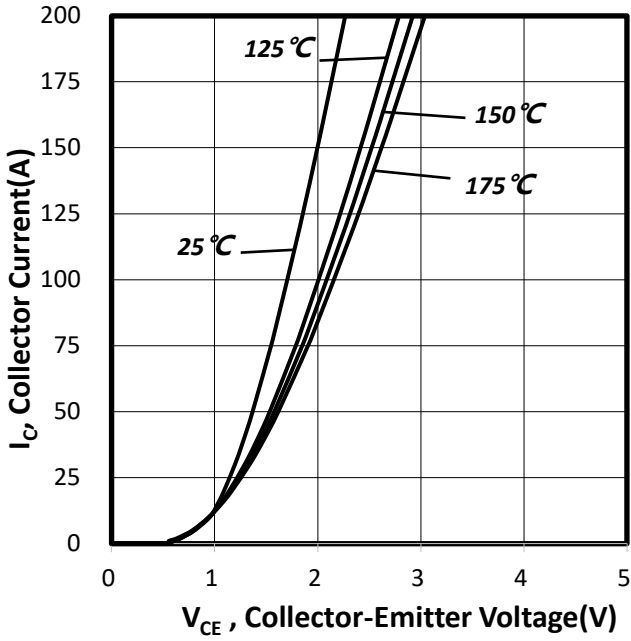


Figure 5. Typical $V_{CE(sat)}$ - I_c characteristic ($V_{GE}=15V$)

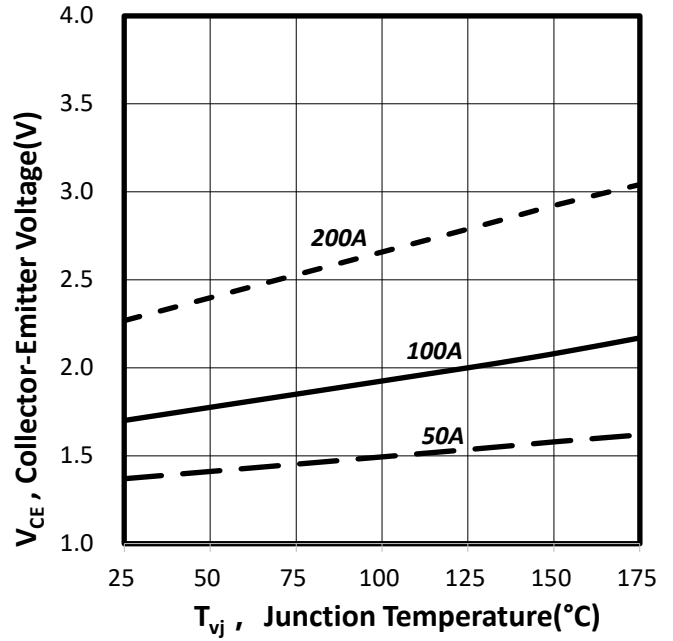


Figure 6. Typical $V_{CE(sat)}$ - T_{vj} characteristic ($V_{GE}=15V$)

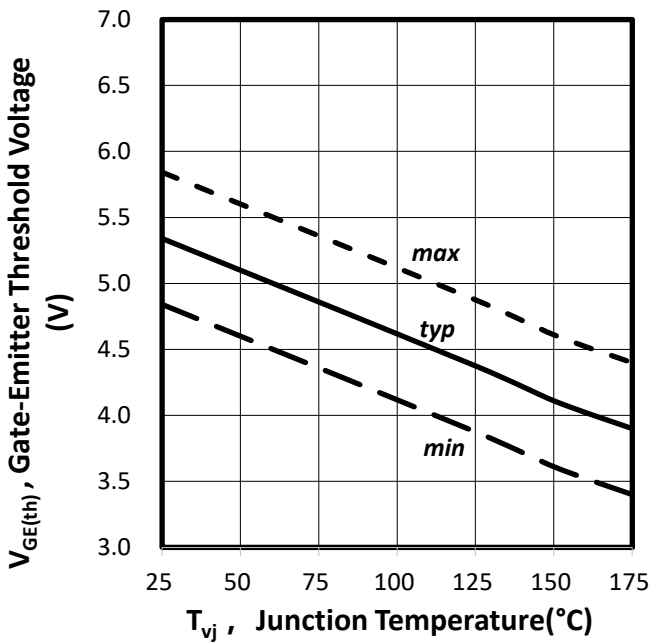


Figure 7. $V_{GE(th)}$ - T_{vj} characteristic ($I_c=2.4mA$)

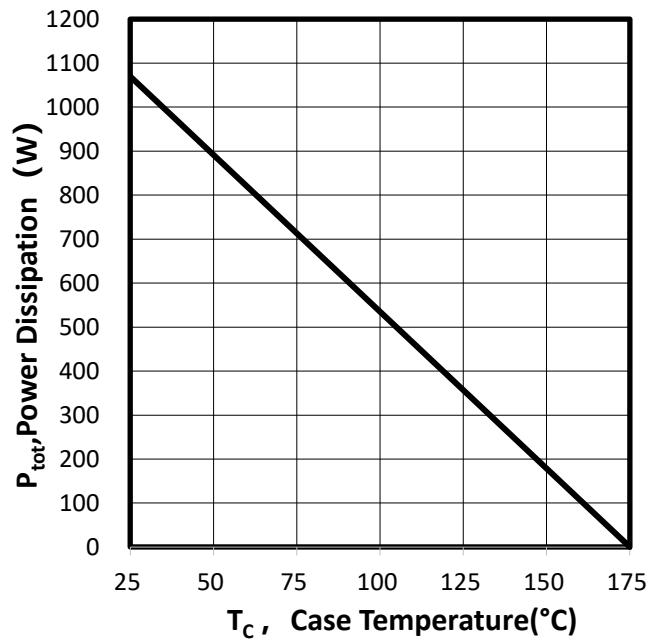


Figure 8. Power dissipation as a function of case temperature ($T_{vj} \le 175^\circ C$)

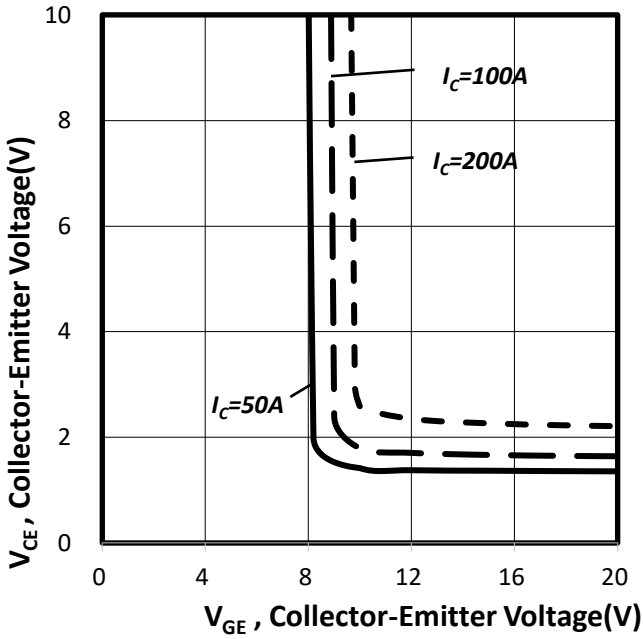


Figure 9. Typical $V_{CE(sat)}-V_{GE(th)}$ characteristic ($T_{vj}=25^{\circ}C$)

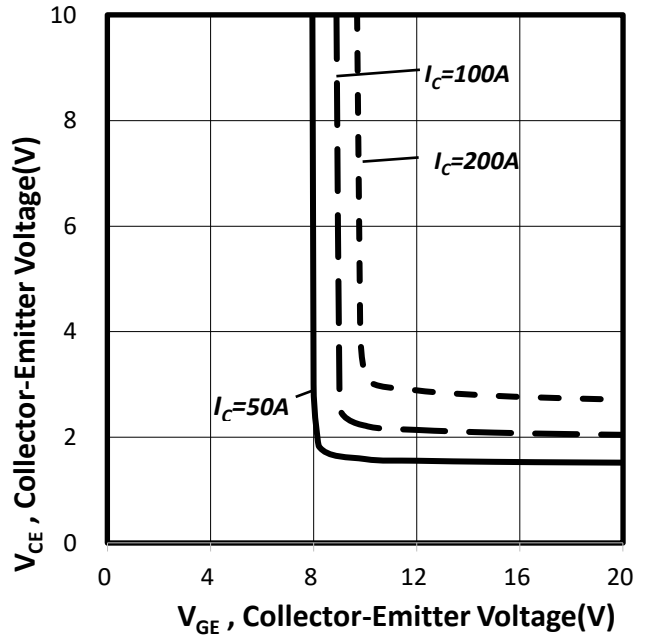


Figure 10. Typical $V_{CE(sat)}-V_{GE(th)}$ characteristic ($T_{vj}=125^{\circ}C$)

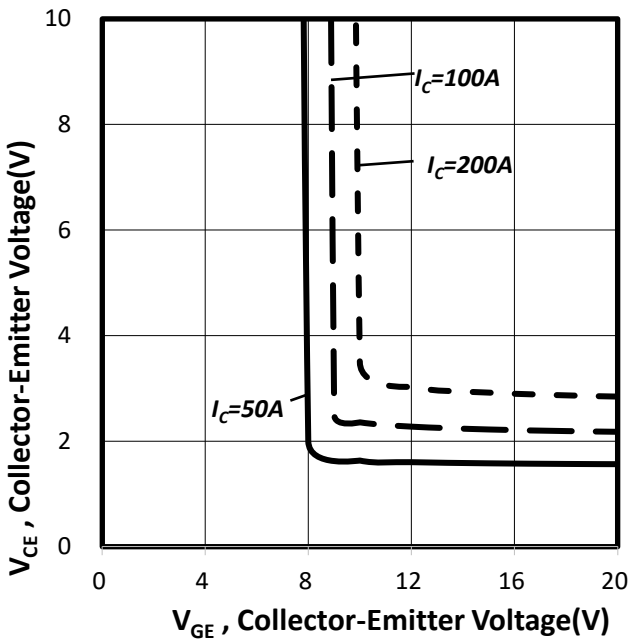


Figure 11. Typical $V_{CE(sat)}-V_{GE(th)}$ characteristic ($T_{vj}=150^{\circ}C$)

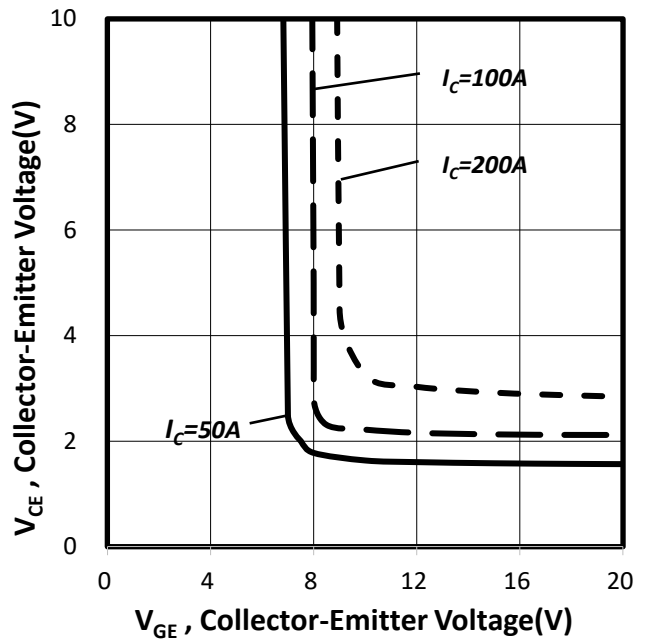


Figure 12. Typical $V_{CE(sat)}-V_{GE(th)}$ characteristic ($T_{vj}=175^{\circ}C$)

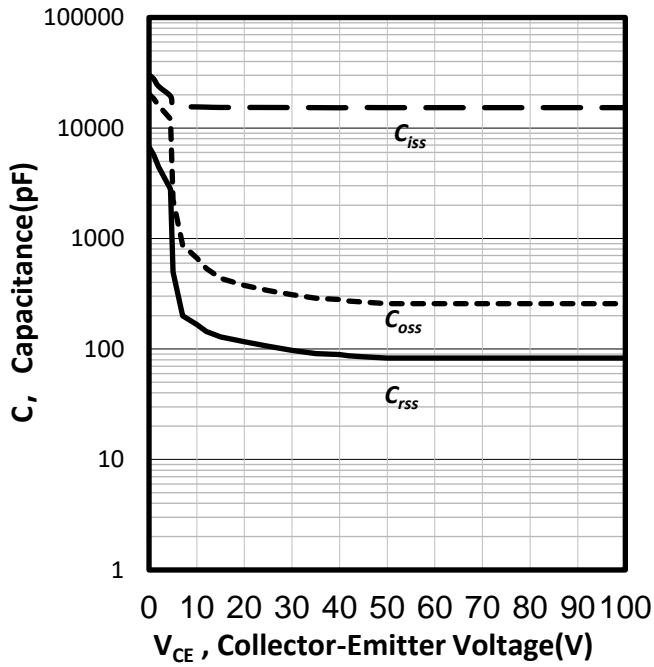


Figure 13. Typical capacitance as a function of collector-emitter voltage (V_{GE}=0V f=1MHz)

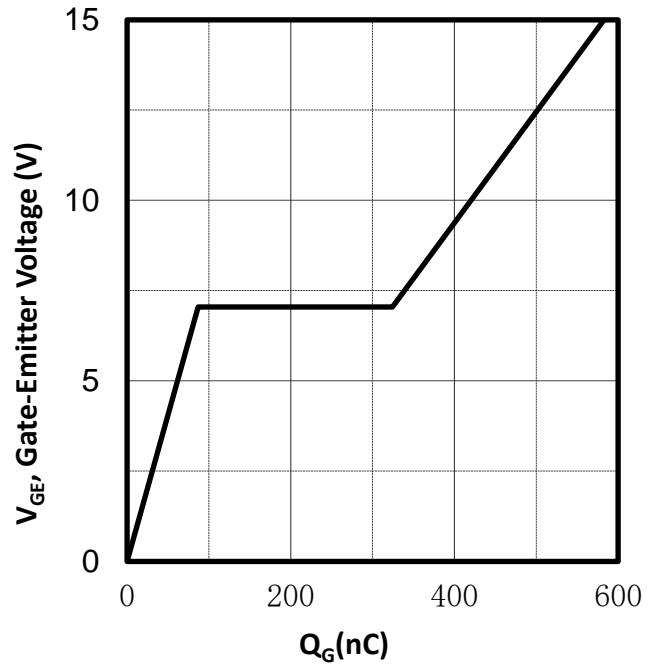


Figure 14. Typical gate charge (V_{CE}=600V)

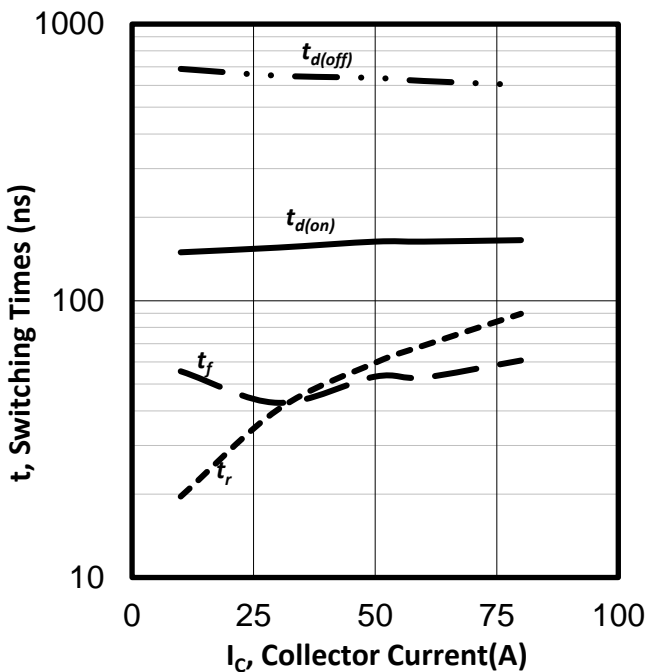


Figure 15. Typical switching times as a function of collector current (inductive load, T_{vj}=25°C V_{CE}=600V V_{GE}=0/15V R_G=10Ω)

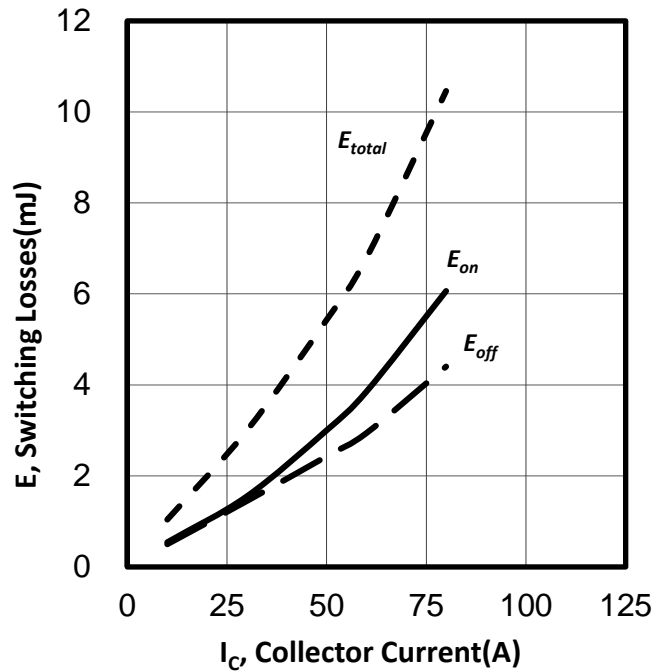


Figure 16. Typical switching energy losses as a function of collector current (inductive load, T_{vj}=25°C V_{CE}=600V V_{GE}=0/15V R_G=10Ω)

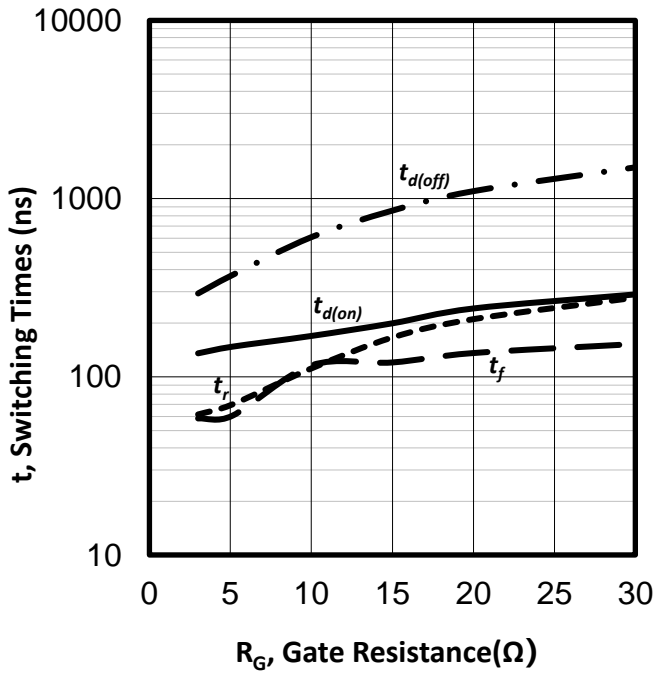


Figure 17. Typical switching times as a function of gate resistor
(inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

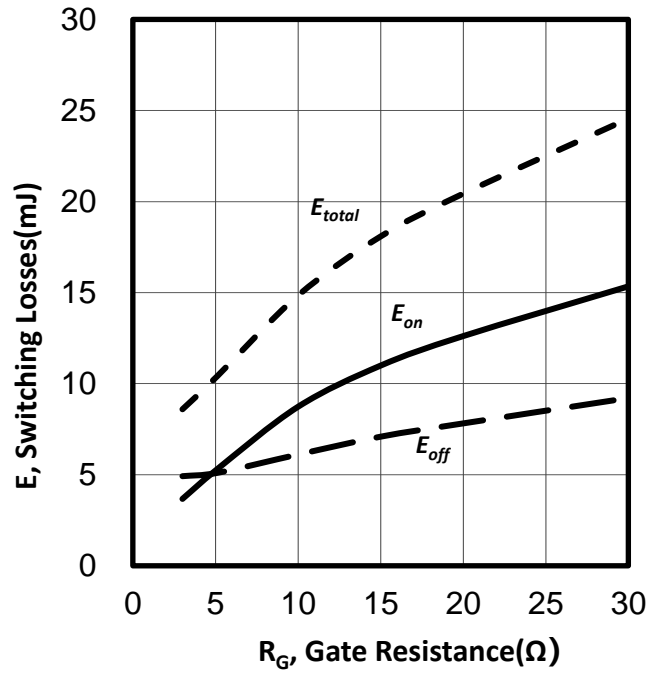


Figure 18. Typical switching energy losses as a function of gate resistor
(inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

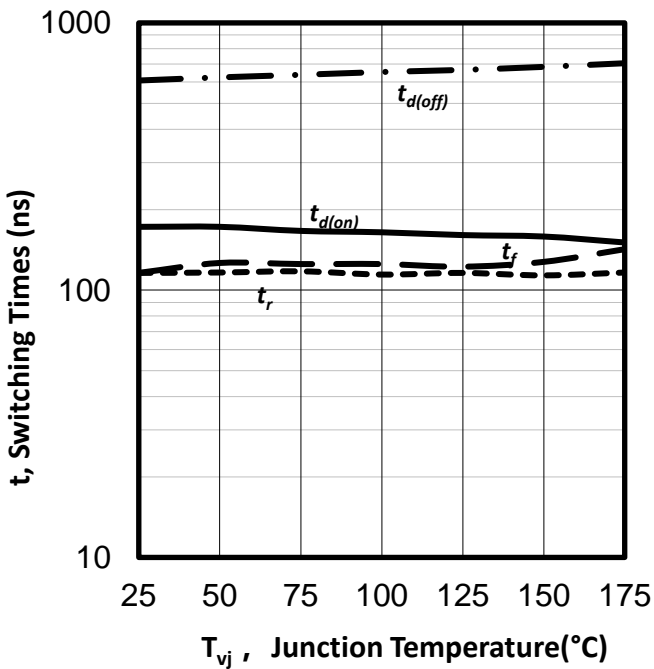


Figure 19. Typical switching times as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$
 $I_C=100\text{A}$ $R_G=10\Omega$)

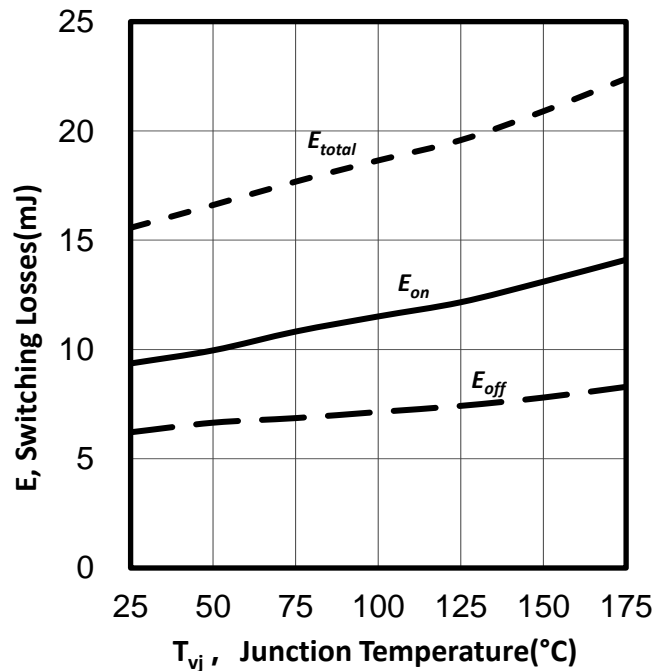


Figure 20. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$
 $I_C=100\text{A}$ $R_G=10\Omega$)

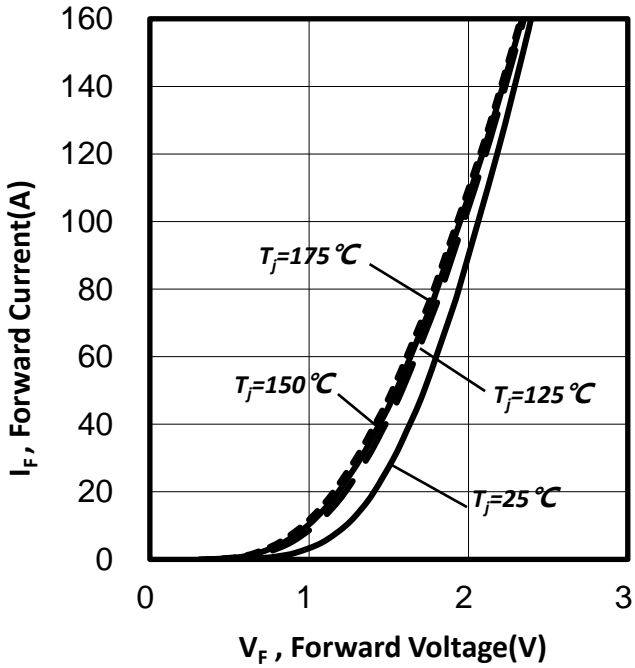


Figure 21. Typical diode forward current as a function of forward voltage

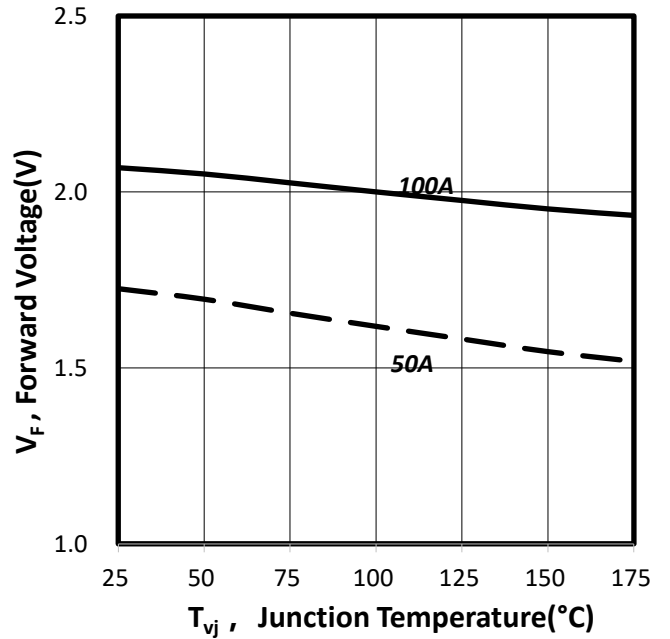


Figure 22. Typical diode forward voltage as a function of junction temperature

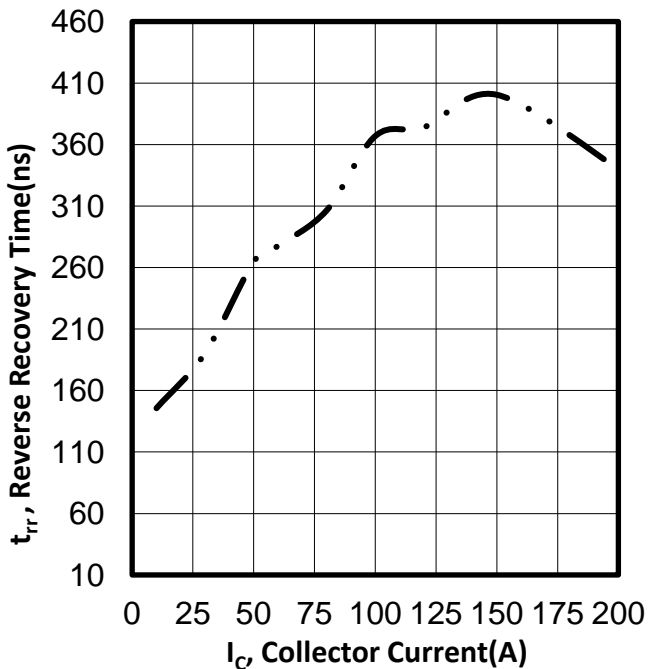


Figure 23. Typical reverse recovery time as a function of collector current (inductive load, $T_{vj}=25^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=10\Omega$)

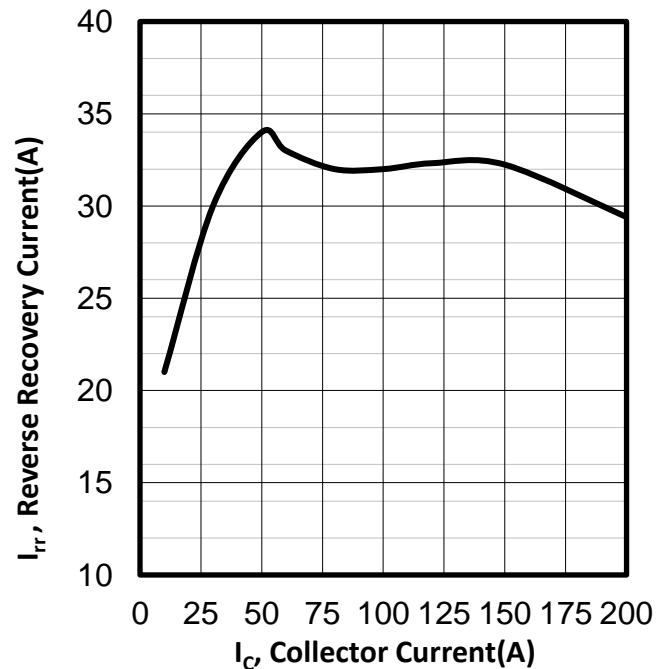


Figure 24. Typical reverse recovery current as a function of collector current (inductive load, $T_{vj}=25^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=10\Omega$)

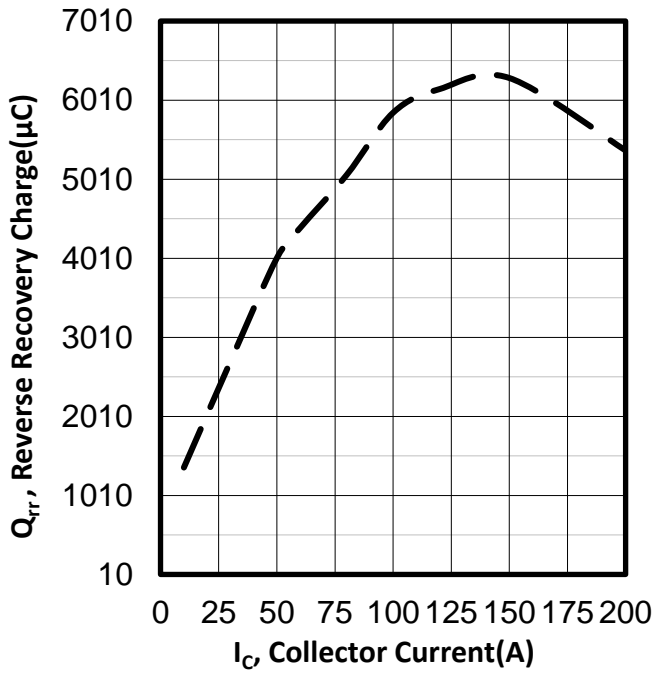


Figure 25. Typical reverse recovery charge as a function of collector current
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $R_G=10\Omega$)

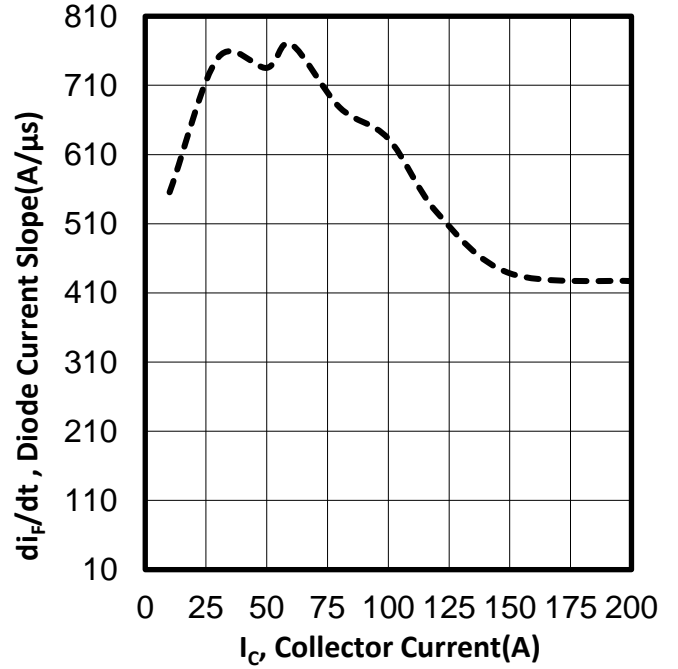


Figure 26. Typical diode current slope as a function of collector current
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $R_G=10\Omega$)

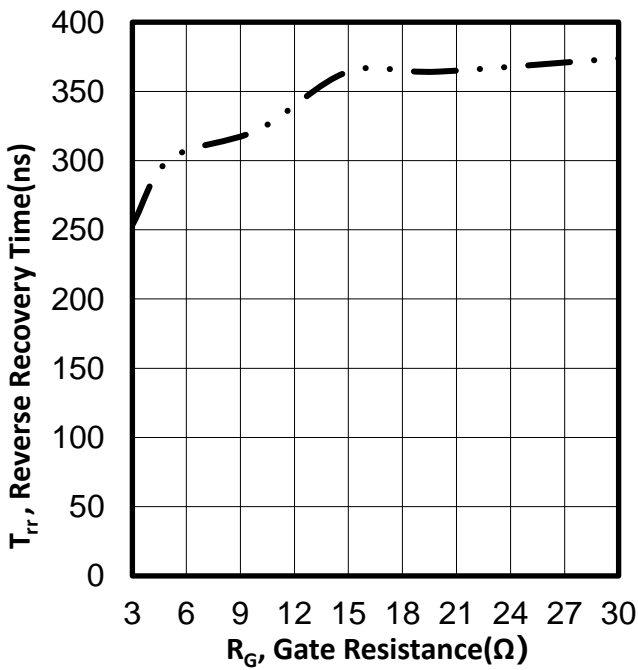


Figure 27. Typical reverse recovery time as a function of gate resistor
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

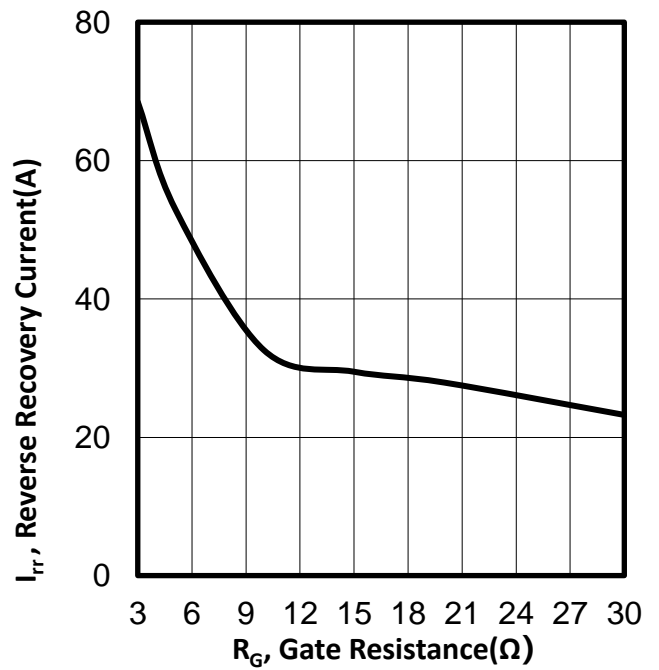


Figure 28. Typical reverse recovery current as a function of gate resistor
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

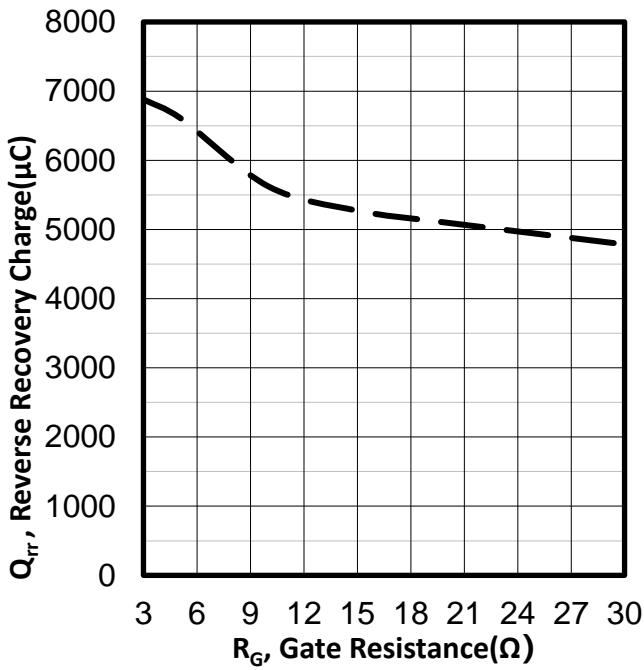


Figure 29. Typical reverse recovery charge as a function of gate resistor
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

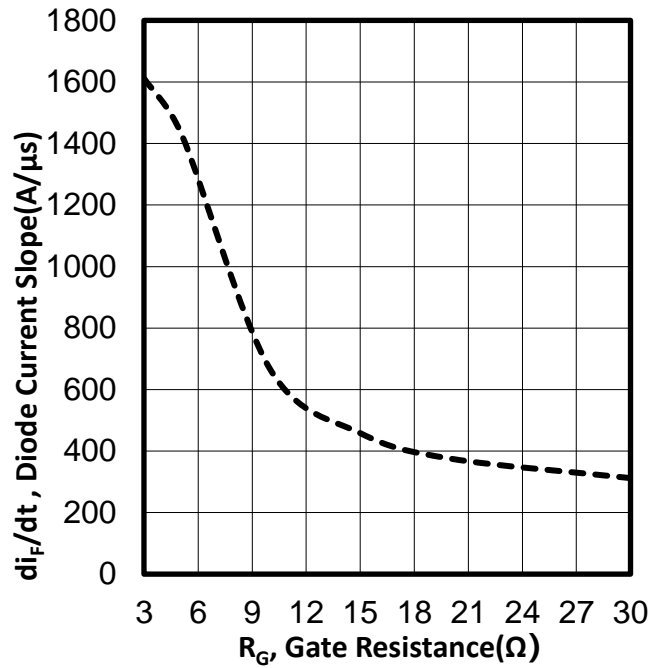


Figure 30. Typical diode current slope as a function of gate resistor
 (inductive load, $T_{vj}=25^{\circ}\text{C}$
 $V_{CE}=600\text{V}$ $V_{GE}=0/15\text{V}$ $I_C=100\text{A}$)

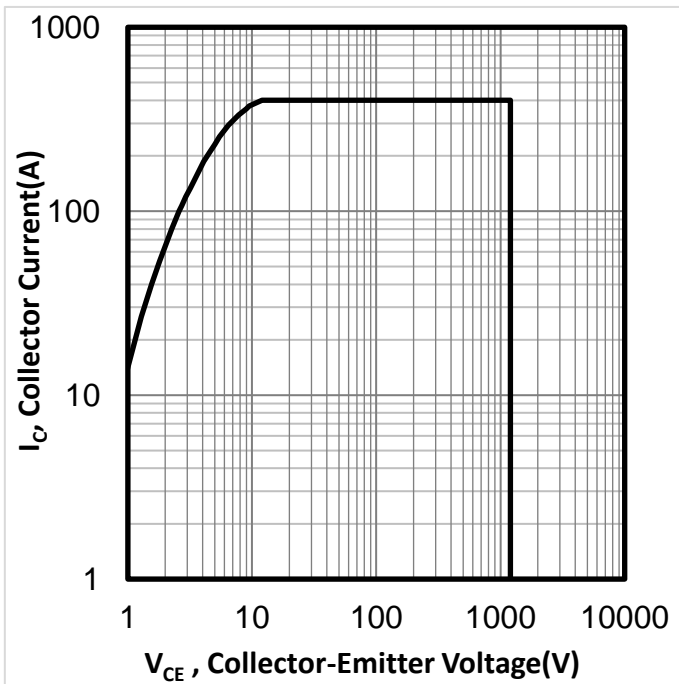


Figure 31. IGBT reverse bias safe operating area
 ($T_{vj}\leq 175^{\circ}\text{C}$ $V_{GE}=15\text{V}$)

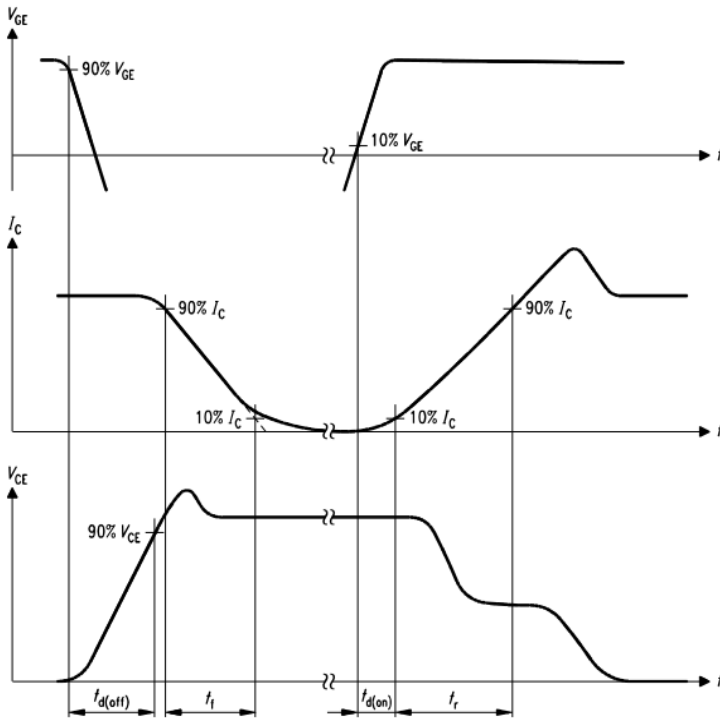


Figure A. Definition of switching times

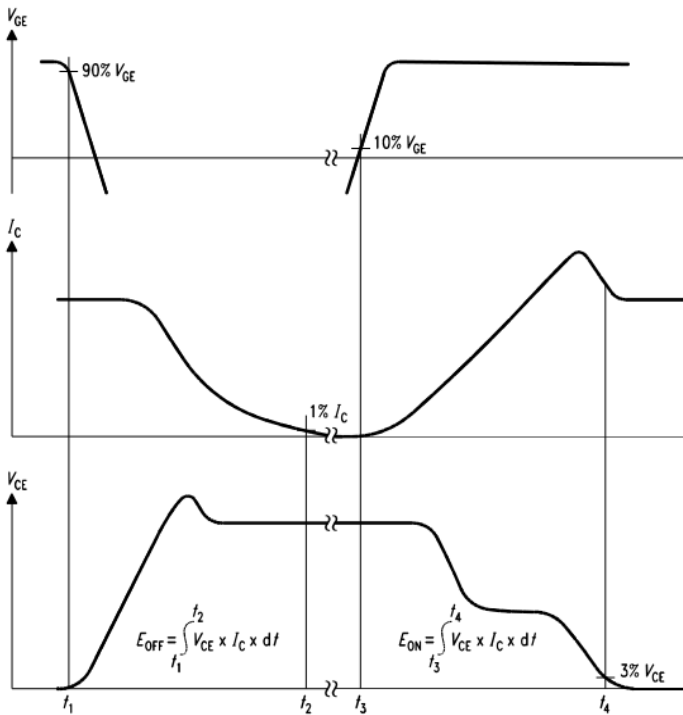


Figure B. Definition of switching losses

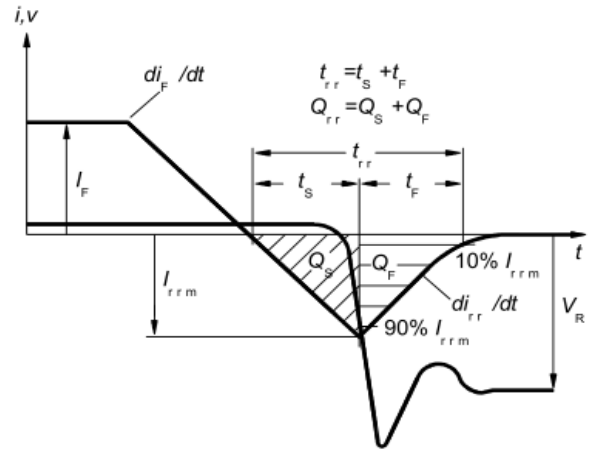


Figure C. Definition of diodes switching characteristics

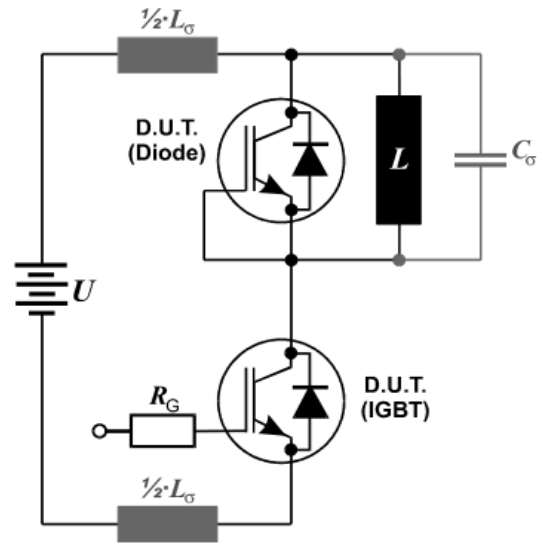
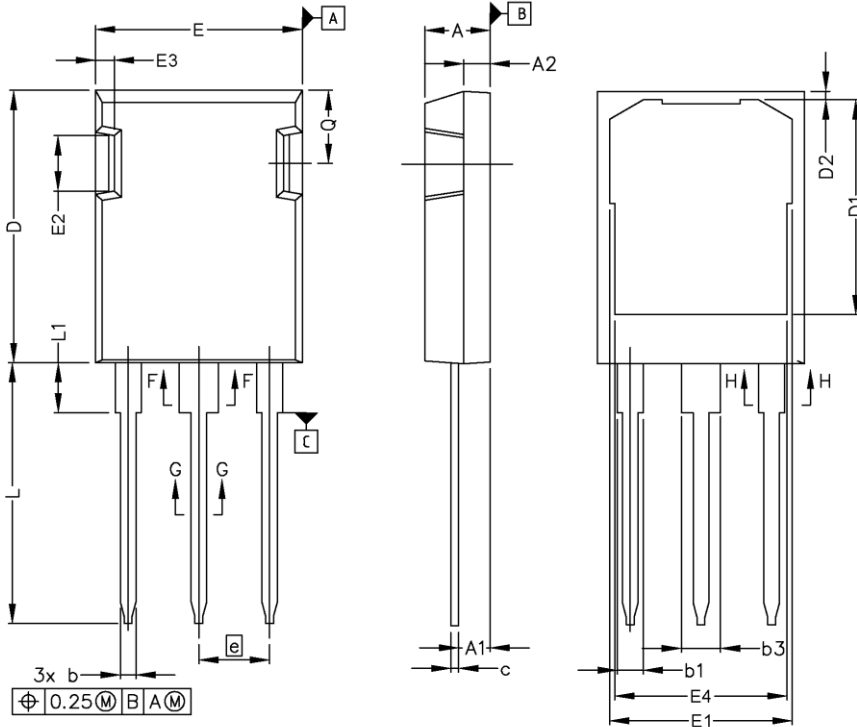


Figure D. Switching test circuit

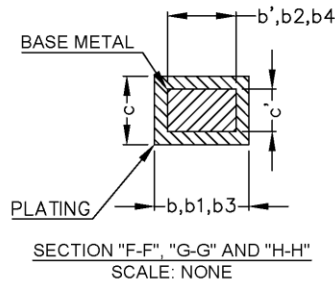
TO-247-3L Plus



SYMBOL	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.50	0.80
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	3.70	4.00
Q	5.49	6.00

NOTE:
 1. ALL METAL SURFACES, TIN PLATED, EXCEPT AREA OF CUT
 2. DIMENSIONING & TOLERANCING CONFIRM TO ASME Y14.5M-1994
 3. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
 4. THIS DRAWING WILL MEET ALL DIMENSIONS REQUIREMENT OF JEDEC outlines TO-247 AD.

- 1 - GATE
- 2 - DRAIN (COLLECTOR)
- 3 - SOURCE (EMITTER)
- 4 - DRAIN (COLLECTOR)





Revision History

Revision	Subjects (major changes since last revision)	Date
1.0	Initial version	2022.5

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